Surface Mount Ultrafast Power Rectifier

Plastic SOD-123FL Package

This SOD–123FL ultrafast rectifier provides fast switching performance with soft recovery in a compact thermally efficient package. Its compact footprint makes it ideally suited to portable and automotive applications where board space is at a premium. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.

Features

- Fast Soft Switching for Reduced EMI and Higher Efficiency
- Low Profile Maximum Height of 1.0 mm
- Small Footprint Footprint Area of 5.94 mm²
- NRV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC–Q101 Qualified and PPAP Capable
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant

Mechanical Characteristics:

- Case: Molded Epoxy
- Epoxy Meets UL 94 V-0 @ 0.125 in
- Weight: 11.7 mg (Approximately)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Maximum for 10 Seconds
- MSL 1

Applications

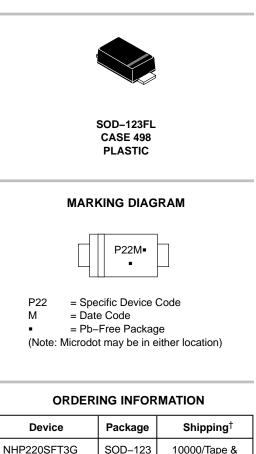
- Instrumentation
- Output Rectification in Switching Power Supplies Including Mini Adapters and Flat Panel Display
- LED Lighting
- Freewheeling Diode Where Space is at a Premium
- Engine Control
- Infotainment and Other Space Constrained Center–stack Applications



ON Semiconductor®

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ULTRAFAST RECTIFIER 2.0 AMPERES 200 VOLTS



(Pb-Free)

SOD-123

(Pb-Free)

†For information on tape and reel specifications,

including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

NRVHP220SFT3G

Reel

10000/Tape &

Reel

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	200	V
Average Rectified Forward Current $(T_L = 140^{\circ}C)$	Ι _Ο	2.0	A
Peak Repetitive Forward Current (Square Wave, 20 kHz, T_L = 135°C)	I _{FRM}	4.0	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	I _{FSM}	40	A
Storage and Operating Junction Temperature Range (Note 1)	T _{stg} , T _J	-65 to +175	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. The heat generated must be less than the thermal conductivity from

Junction–to–Ambient: $dP_D/dT_J < 1/R_{\theta JA}$.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Lead (Note 2)	Ψ_{JCL}	23	°C/W
Thermal Resistance, Junction-to-Ambient (Note 2)	R_{\thetaJA}	85	°C/W
Thermal Resistance, Junction-to-Ambient (Note 3)	$R_{ hetaJA}$	330	°C/W

ELECTRICAL CHARACTERISTICS

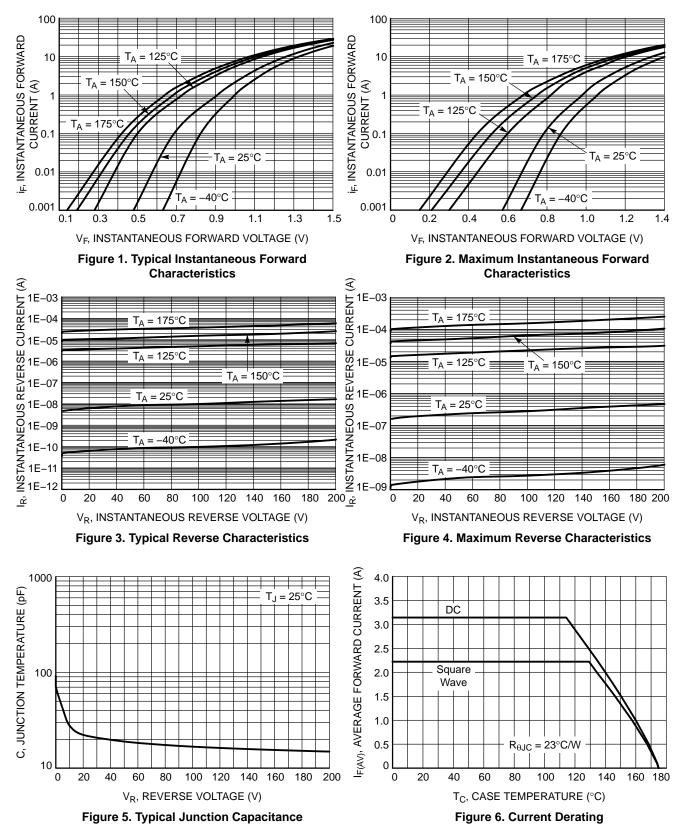
Characteristic	Symbol	Value	Unit
	VF	1.0 1.05 0.86 0.90	V
Maximum Instantaneous Reverse Current (Note 4) (Rated dc Voltage, $T_J = 25^{\circ}C$) (Rated dc Voltage, $T_J = 125^{\circ}C$)	۱ _R	0.5 35	μΑ
Reverse Recovery Time $I_F = 2.0 \text{ A}; V_R = 30 \text{ V}; \text{ dl/dt} = 50 \text{ A/}\mu\text{s}$ $T_J = -40^{\circ}\text{C} \text{ to } 150^{\circ}\text{C}$	t _{rr}	50	ns

2. Mounted with 700 mm² copper pad size (Approximately 1 in²) 1 oz FR4 Board.

3. Mounted with pad size approximately 20 mm² copper, 1 oz FR4 Board. 4. Pulse Test: Pulse Width \leq 380 µs, Duty Cycle \leq 2.0%.

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

TYPICAL CHARACTERISTICS



TYPICAL CHARACTERISTICS

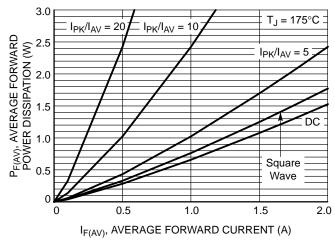


Figure 7. Forward Power Dissipation

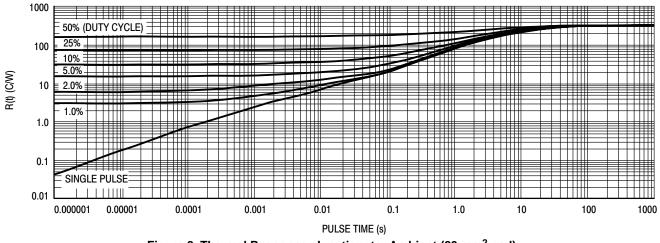
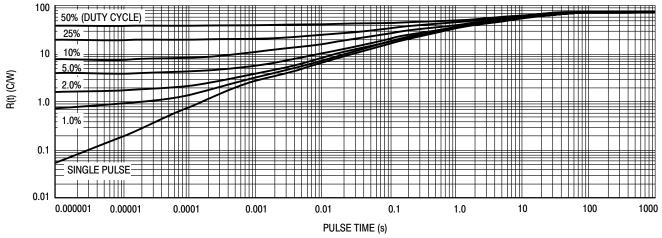


Figure 8. Thermal Response, Junction-to-Ambient (20 mm² pad)



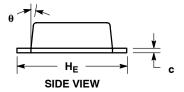


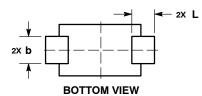
DATE 10 MAY 2013



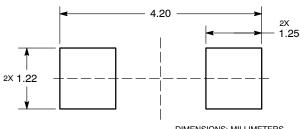


Ε D POLARITY INDICATOR OPTIONAL AS NEEDED TOP VIEW





RECOMMENDED SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

SOD-123FL **CASE 498 ISSUE D**

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END VIEW

NOTES:

- 1. 2.
- 3.
- LES: DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. CONTROLLING DIMENSION: MILLIMETER. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH. DIMENSIONS D AND J ARE TO BE MEASURED ON FLAT SECTION OF THE LEAD: BETWEEN 0.10 AND 0.25 MM FROM THE LEAD TIP. 4.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α	0.90	0.95	0.98	0.035	0.037	0.039
A1	0.00	0.05	0.10	0.000	0.002	0.004
b	0.70	0.90	1.10	0.028	0.035	0.043
С	0.10	0.15	0.20	0.004	0.006	0.008
D	1.50	1.65	1.80	0.059	0.065	0.071
Е	2.50	2.70	2.90	0.098	0.106	0.114
L	0.55	0.75	0.95	0.022	0.030	0.037
ΗE	3.40	3.60	3.80	0.134	0.142	0.150
θ	0°	-	8°	0°	_	8°

GENERIC **MARKING DIAGRAM***



XXX = Specific Device Code = Date Code Μ -= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " •", may or may not be present.

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